PD IEC/TR 62878-2-2:2015

BSI Standards Publication

Device embedded substrate

Part 2-2: Guidelines — Electrical testing

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The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its secretary.

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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DEVICE EMBEDDED SUBSTRATE –

Part 2-2: Guidelines – Electrical testing

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IEC TR 62878-2-2, which is a Technical Report, has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this Technical Report is based on the following documents:

Enquiry draft	Report on voting
91/1220/DTR	91/1245/RVC

Full information on the voting for the approval of this Technical Report can be found in the report on voting indicated in the above table.

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The French version of this Technical Report has not been voted upon.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62878 series, published under the general title *Device embedded substrate*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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